



## Recent Advances in Additive Manufacturing: From Building Processes to Materials Properties

Guest Editors:

**Prof. Dr. Paolo Fino**

DISAT - Department of Applied  
Science and Technology,  
Politecnico di Torino, 10129  
Turin, Italy

**Dr. Alberta Aversa**

Department of Applied Science  
and Technology, Politecnico di  
Torino, Corso Duca degli Abruzzi  
24, 10129 Torino, Italy

Deadline for manuscript  
submissions:

**closed (20 November 2021)**

### Message from the Guest Editors

Dear Colleagues,

At present, additive manufacturing (AM) processing technologies are continuously gaining interest in many industrial fields. The main advantages of these processes are undoubtedly related to the possibility of producing complex components and customized parts without the need of dedicated tools.

The rapid advancements of building processes have to be supported by an understanding of the AM materials' properties and of their correlations with the building conditions. The unique AM building processes can on the one hand cause different material properties and, on the other hand, open new possibilities for the development of materials characterized by interesting properties and specific functionalities.

This Special Issue will address the recent advancements in the characterization of AM materials. Potential topics may include:

- New methodology for materials additive manufacturing development;
- New materials for additive manufacturing;
- Advanced characterizations of AM materials;
- Properties of AM materials;
- Materials modeling for AM development.





an Open Access Journal by MDPI

## Editor-in-Chief

**Prof. Dr. Giulio Nicola Cerullo**

Dipartimento di Fisica,  
Politecnico di Milano, Piazza L.  
da Vinci 32, 20133 Milano, Italy

## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

## Author Benefits

**Open Access:** free for readers, with article processing charges (APC) paid by authors or their institutions.

**High Visibility:** indexed within Scopus, SCIE (Web of Science), Inspec, CAPlus / SciFinder, and other databases.

**Journal Rank:** JCR - Q2 (*Engineering, Multidisciplinary*) / CiteScore - Q1 (*General Engineering*)

## Contact Us

---

Applied Sciences Editorial Office  
MDPI, St. Alban-Anlage 66  
4052 Basel, Switzerland

Tel: +41 61 683 77 34  
[www.mdpi.com](http://www.mdpi.com)

[mdpi.com/journal/applsci](http://mdpi.com/journal/applsci)  
[applsci@mdpi.com](mailto:applsci@mdpi.com)  
X@Applsci